Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]
HP Envy 14 Sleekbook

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

#### 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. remove log low
2. remove K_LOCK_BRK
3. remove HDD assy
4. remove Battery Module
5. remove SSD Card
6. remove I/O Board Module
7. remove WWAN/WLAN Card
8. remove FAN Module
9. remove Card Reader Board
10. remove Main Board
11. remove RTC Battery
12. remove Thermal Module
13. remove DC-IN Bracket
14. remove DC-IN Cable
15. remove Subwoofer Module
16. remove Speaker L
17. remove LCD Module
18. remove Key Board Bracket
19. remove Key Board
20. remove TP Module
21. remove Power Board
22. divide Display assy (remove LCD Bezel)
23. divide Display assy (remove Hinge R)
24. divide Display assy (remove Hinge L)
25. divide Display assy (remove WLAN Module)
26. divide Display assy (remove LCD Panel)
27. divide Display assy (remove Webcam)
28. divide Display assy (remove LCD LVDS cable)

#### 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

#### 3.21 Total part disassembly

PSG instructions for this template are available at [EL-MF877-01](#)
3.22 Remove battery module
3.23 Remove service door
3.24 LCD module set disassembly
3.25 Top case disassembly
3.26 Thermal module and mother board disassembly
3.27 Bottom case disassembly
Step 1 Remove log low

Step 2 Remove K_LOCK_BRK

Step 3 Remove HDD

Step 4 Remove Battery module

Step 5 Remove SDD Card

Step 6 Remove I/O Board

PSG instructions for this template are available at EL-MF877-01
Step 7 Remove WWAN/WLAN Card

Step 8 Remove FAN Module

Step 9 Remove Card Reader Board

Step 10 Remove Main Board

Step 11 Remove RTC Battery

Step 12 Remove Thermal Module

PSG instructions for this template are available at [EL-MF877-01](#)
Step 13 Remove DC-IN Bracket

Step 14 Remove DC-IN

Step 15 Remove SUBWOOFER

Step 16 Remove Speaker L

Step 17 Remove LCD Module

Step 18 Remove Key Board Bracket

PSG instructions for this template are available at EL-MF877-01
Step 19 Remove Key Board

Step 20 Remove Touch Pad Module

Step 21 Remove Power Board

Step 22 Remove LCD Bezel

Step 23 Remove Hinge R

Step 24 Remove Hinge L
Step 25 Remove WLAN Module

Step 26 Remove LCD Panel

Step 27 Remove Webcam

Step 28 Remove LVDS Cable